nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

| Supplier | | User Part Number | | | | | |
|---|------------------------------------|--|-------------|-----------|------------|-----------|--|
| Nexperia B.V. | | BAV23C-Q | | | | | |
| Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | Part Description | | | | | |
| | | Nexperia DHAM Small Signal Bipolar Diode | | | | | |
| | | SMD package | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | |
| | TEST | | | | | | |
| | Pre- and Post-Stress | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | |
| | | JESD22-A113 | ., | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | | |
| | PC | Soak Tamb = $85 ^{\circ}$ C, RH = 85% | 168 hours | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 | |
| | | MIL-STD-750-1 | | | | | |
| | HTRB | M1038 Method A | | | | | |
| | | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | |
| # B1 | Bias | reverse voltage | 1000 hours | 110 | 4920 | 0 | |
| | | · · · · · · · · · · · · · · · · · · · | 1000 110010 | 110 | 1920 | 0 | |
| | тс | JESD22-A104 | | | | | |
| # A4 | Temperature Cycling | -65 °C to Timax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 | |
| | | | 1000 070.00 | 011 | 1.000 | 0 | |
| | UHAST | JESD22-A118 | | | | | |
| # A3 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | | | | | |
| # A3 alt | | JESD22-A102 | —96 hours | 311 | 14080 | 0 | |
| | AC | Tamb = $121 ^{\circ}$ C, RH = $100 ^{\circ}$ | | | | | |
| | Autoclave | Pressure = $205 \text{ kPa} (29.7 \text{ psia})$ | | | | | |
| # AJ alt | Adociave | | | | | | |
| | H3TRB | JESD22-A101 | | | | | |
| | High Humidity High | Tamb = $85 ^{\circ}$ C, RH = 85% , VR = 80% of | | | | | |
| # A2 alt | Temperature Reverse Bias | | 1000 hours | 311 | 14080 | 0 | |
| # AZ dil | remperature reverse blas | | 1000 110015 | 211 | 14000 | 0 | |
| | 101 | MIL-STD-750 Method 1037 | | | | | |
| # AF | IOL Intermittent Operating Life | ton = toff, devices powered to insure ΔT_j = | 1000 hours | 212 | 14120 | 0 | |
| # A5 | Intermittent Operating Life | 100 °C 101 15000 Cycles | 1000 hours | 312 | 14120 | 0 | |
| | Bell | 150000 4111 | | | | | |
| # 60 | RSH | JESD22-A111 | 10 - | 260 | 0070 | 0 | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 | |
| | SD California hillion | 1 CTD 000 | | 222 | | | |
| # C10 | Solderability | J-STD-002 | | 222 | 6660 | 0 | |

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|----------------------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Small Signal Bipolar Diode | 4920 | 0 | 0,86 | 1,16E+09 |

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